2SA2009

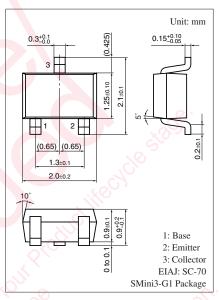
Silicon PNP epitaxial planar type

For low-frequency high breakdown voltage amplification

Features

- \bullet High collector-emitter voltage (Base open) V_{CEO}
- Low noise voltage NV
- S-Mini type package, allowing downsizing and thinning of the equipment and automatic insertion through the tape packing.

Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Symbol Rating Unit Collector-base voltage (Emitter open) V_{CBO} -120V V Collector-emitter voltage (Base open) V_{CEO} -120-5 V Emitter-base voltage (Collector open) V_{EBO} -20 Collector current I_C mA -50 Peak collector current I_{CP} mA Collector power dissipation P_C 150 mW °C Junction temperature Ti 150 Storage temperature -55 to +150 °C T_{stg}



Marking Symbol: AR

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-120	S		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 {\rm mA}, I_{\rm B} = 0$		0		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \ \mu A, I_{\rm C} = 0$				V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50 \text{ V}, I_E = 0$			-100	nA
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -50 \text{ V}, I_B = 0$			-1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = -5 \text{ V}, I_C = -2 \text{ mA}$	180		700	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -20 \text{ mA}, I_{\rm B} = -2 \text{ mA}$			- 0.6	V
Transition frequency	f _T	$V_{CB} = -5 V, I_E = 2 mA, f = 200 MHz$ 200			MHz	
Noise voltage NV		$V_{CE} = -40 \text{ V}, I_C = -1 \text{ mA}, G_V = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega$, Function = FLAT			130	mV

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S	Т	
h _{FE}	180 to 360	260 to 520	360 to 700	

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